

# XC7SH04

## Inverter

Rev. 01 — 1 September 2009

Product data sheet

## 1. General description

XC7SH04 is a high-speed Si-gate CMOS device. It provides an inverting buffer.

## 2. Features

- Symmetrical output impedance
- High noise immunity
- Low power dissipation
- Balanced propagation delays
- SOT353-1 and SOT753 package options
- ESD protection:
  - ◆ HBM JESD22-A114E: exceeds 2000 V
  - ◆ MM JESD22-A115-A: exceeds 200 V
  - ◆ CDM JESD22-C101C: exceeds 1000 V
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
XC7SH04GW	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
XC7SH04GV	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SC-74A	plastic surface-mounted package; 5 leads	SOT753

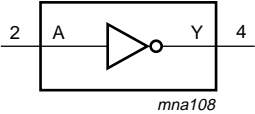
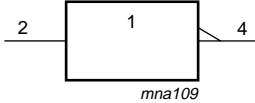
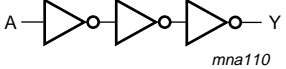
## 4. Marking

**Table 2. Marking codes**

Type number	Marking <sup>[1]</sup>
XC7SH04GW	fC
XC7SH04GV	f04

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

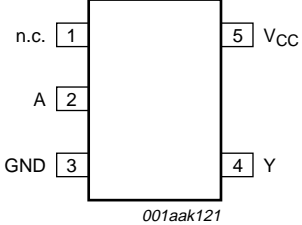
## 5. Functional diagram

 <p><b>Fig 1. Logic symbol</b></p>	 <p><b>Fig 2. IEC logic symbol</b></p>	 <p><b>Fig 3. Logic diagram</b></p>
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## 6. Pinning information

### 6.1 Pinning

**XC7SH04**



**Fig 4. Pin configuration SOT353-1 (TSSOP5) and SOT753 (SC-74A)**

### 6.2 Pin description

**Table 3. Pin description**

Symbol	Pin	Description
n.c.	1	not connected
A	2	data input
GND	3	ground (0 V)
Y	4	data output
V <sub>CC</sub>	5	supply voltage

## 7. Functional description

**Table 4. Function table**

*H = HIGH voltage level; L = LOW voltage level*

Input	Output
A	Y
L	H
H	L

## 8. Limiting values

**Table 5. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7.0	V
$V_I$	input voltage		-0.5	+7.0	V
$I_{IK}$	input clamping current	$V_I < -0.5$ V	-20	-	mA
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	[1] -	$\pm 20$	mA
$I_O$	output current	$-0.5$ V $< V_O < V_{CC} + 0.5$ V	-	$\pm 25$	mA
$I_{CC}$	supply current		-	75	mA
$I_{GND}$	ground current		-75	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[2] -	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For both TSSOP5 and SC-74A packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.

## 9. Recommended operating conditions

**Table 6. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		2.0	5.0	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$	-	-	100	ns/V
		$V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	-	-	20	ns/V

## 10. Static characteristics

**Table 7. Static characteristics**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0 \text{ V}$	1.5	-	-	1.5	-	1.5	-	V
		$V_{CC} = 3.0 \text{ V}$	2.1	-	-	2.1	-	2.1	-	V
		$V_{CC} = 5.5 \text{ V}$	3.85	-	-	3.85	-	3.85	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0 \text{ V}$	-	-	0.5	-	0.5	-	0.5	V
		$V_{CC} = 3.0 \text{ V}$	-	-	0.9	-	0.9	-	0.9	V
		$V_{CC} = 5.5 \text{ V}$	-	-	1.65	-	1.65	-	1.65	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$								
		$I_O = -50 \mu\text{A}; V_{CC} = 2.0 \text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -50 \mu\text{A}; V_{CC} = 3.0 \text{ V}$	2.9	3.0	-	2.9	-	2.9	-	V
		$I_O = -50 \mu\text{A}; V_{CC} = 4.5 \text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.58	-	-	2.48	-	2.40	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH} \text{ or } V_{IL}$								
		$I_O = 50 \mu\text{A}; V_{CC} = 2.0 \text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50 \mu\text{A}; V_{CC} = 3.0 \text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50 \mu\text{A}; V_{CC} = 4.5 \text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4.0 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	-	0.36	-	0.44	-	0.55	V
$I_I$	input leakage current	$V_I = 5.5 \text{ V or GND}; V_{CC} = 0 \text{ V to } 5.5 \text{ V}$	-	-	0.1	-	1.0	-	2.0	$\mu\text{A}$
		$V_I = V_{CC} \text{ or GND}; I_O = 0 \text{ A}; V_{CC} = 5.5 \text{ V}$	-	-	1.0	-	10	-	40	$\mu\text{A}$
$C_I$	input capacitance		-	1.5	10	-	10	-	10	pF

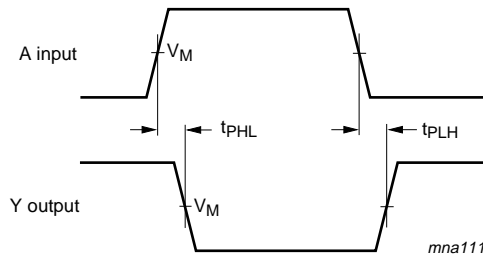
## 11. Dynamic characteristics

**Table 8. Dynamic characteristics**  
*GND = 0 V. For test circuit see Figure 6.*

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t <sub>pd</sub>	propagation delay	A to Y; see Figure 5 [1]								
		V <sub>CC</sub> = 3.0 V to 3.6 V [2]								
		C <sub>L</sub> = 15 pF	-	4.3	7.1	1.0	8.5	1.0	11.0	ns
		C <sub>L</sub> = 50 pF	-	6.1	10.6	1.0	12	1.0	14.5	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V [3]								
		C <sub>L</sub> = 15 pF	-	3.1	5.5	1.0	6.5	1.0	7.0	ns
		C <sub>L</sub> = 50 pF	-	4.5	7.5	1.0	8.5	1.0	9.5	ns
C <sub>PD</sub>	power dissipation capacitance	per buffer; C <sub>L</sub> = 50 pF; f = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> [4]	-	15	-	-	-	-	-	pF

- [1] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.
- [2] Typical values are measured at V<sub>CC</sub> = 3.3 V.
- [3] Typical values are measured at V<sub>CC</sub> = 5.0 V.
- [4] C<sub>PD</sub> is used to determine the dynamic power dissipation P<sub>D</sub> (μW).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum(C_L \times V_{CC}^2 \times f_o)$  where:  
 f<sub>i</sub> = input frequency in MHz; f<sub>o</sub> = output frequency in MHz;  
 C<sub>L</sub> = output load capacitance in pF;  
 V<sub>CC</sub> = supply voltage in V;  
 $\sum(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

**12. Waveforms**

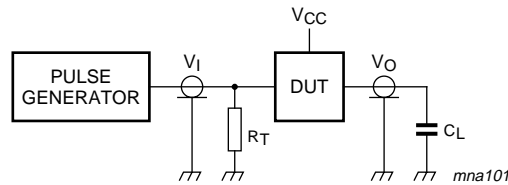


Measurement points are given in [Table 9](#).

**Fig 5. Input (A) to output (Y) propagation delays**

**Table 9. Measurement point**

Type	Input	Input	Output
	$V_I$	$V_M$	$V_M$
XC7SH04	GND to $V_{CC}$	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$



Test data is given in [Table 10](#). Definitions for test circuit:

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

**Fig 6. Load circuitry for switching times**

**Table 10. Test data**

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
XC7SH04	$V_{CC}$	$\leq 3.0$ ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$

13. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mm

SOT353-1



Fig 7. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753



Fig 8. Package outline SOT753 (SC-74A)



## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
XC7SH04_1	20090901	Product data sheet	-	-

## 16. Legal information

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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